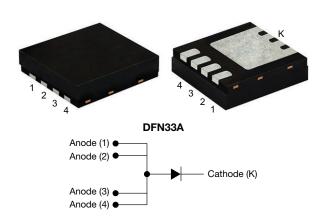


Vishay General Semiconductor

Surface-Mount TMBS® (Trench MOS Barrier Schottky) Rectifier



LINKS TO ADDITIONAL RESOURCES





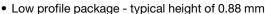






PRIMARY CHARACTERISTICS				
I _{F(AV)}	8 A			
V_{RRM}	100 V			
I _{FSM}	100 A			
V_F at $I_F = 4$ A ($T_J = 125$ °C)	0.52 V			
T _J max.	175 °C			
Package	DFN33A			
Circuit configuration	Single			

FEATURES





 Leadless DFN package with side-wettable flanks suitable for customer AOI (Automatic Optical Inspection)



Very low forward voltage drop by TMBS Gen3 technology

COMPLIANT HALOGEN

- Low power losses, high efficiency
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified available
 - Automotive ordering code; base P/NHM3
- Material categorization: for definitions of compliance please see www.vishav.com/doc?99912

TYPICAL APPLICATIONS

For use in low voltage, high frequency inverters, freewheeling, DC/DC converters, and polarity protection applications.

MECHANICAL DATA

Case: DFN33A

Molding compound meets UL 94 V-0 flammability rating

Base P/N-M3 - halogen-free, RoHS-compliant, and

commercial grade

Base P/NHM3 - halogen-free, RoHS-compliant, and

AEC-Q101 qualified

Terminals: matte tin plated leads, solderable per

J-STD-002 and JESD 22-B102

M3 and HM3 suffix meet JESD 201 class 2 whisker test

MAXIMUM RATINGS (T _A = 25 °C unless otherwise noted)				
PARAMETER	SYMBOL	V8N3M103S	UNIT	
Device marking code		8M13S		
Maximum repetitive peak reverse voltage	V _{RRM}	100	V	
Maximum avarage forward rectified current (fig. 1)	I _{F(AV)} (1)	8	А	
Maximum average forward rectified current (fig. 1)	I _{F(AV)} (2)	2.5	А	
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load	I _{FSM}	100	А	
Operating junction temperature range	T _J ⁽³⁾	-40 to +175	°C	
Storage temperature range	T _{STG}	-55 to +175	°C	

Notes

- (1) With infinite heatsink
- (2) Free air, mounted on FR4 PCB, 2 oz., standard footprint
- (3) The heat generated must be less than the thermal conductivity from junction-to-ambient: dP_D/dT_J < 1/R_{θ,JA}



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ELECTRICAL CHARACTERISTICS (T _J = 25 °C unless otherwise noted)							
PARAMETER	TEST CONDITIONS		SYMBOL	TYP.	MAX.	UNIT	
Instantaneous forward voltage	I _F = 4 A	T _J = 25 °C	V _F ⁽¹⁾	0.58	-	V	
	I _F = 8 A			0.70	0.76		
	I _F = 4 A	T _J = 125 °C		0.52	-		
	I _F = 8 A			0.61	0.66		
Reverse current	V _R = 70 V	T _J = 25 °C T _J = 125 °C	I _R ⁽²⁾	0.0013	ı		
		T _J = 125 °C		0.9	-	mA	
	V _R = 100 V	T _J = 25 °C		-	0.08	IIIA	
		T _J = 125 °C		2	6		
Typical junction capacitance	4.0 V, 1 MHz		CJ	720	i	pF	

Notes

(1) Pulse test: 300 µs pulse width, 1 % duty cycle

(2) Pulse test: pulse width ≤ 5 ms

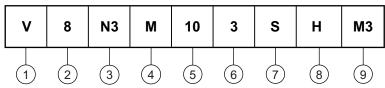
THERMAL CHARACTERISTICS (T _A = 25 °C unless otherwise specified)					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
	R _{0JA} (1)(2)	118	148	°C/W	
Thermal resistance	R _{0JA} (3)	-	65		
	R _{0JM} (4)	3.2	4]	

Notes

- (1) The heat generated must be less than the thermal conductivity from junction-to-ambient: $dP_D/dT_J < 1/R_{\theta JA}$
- (2) Thermal resistance junction-to-ambient to follow JEDEC® 51-2A, device mounted on FR4 PCB, 2 oz., standard footprint
- (3) Thermal resistance junction-to-ambient, free air with device mounted on FR4 PCB, 2 oz., 20 mm x 20 mm pad area
- (4) Thermal resistance junction-to-mount to follow JEDEC 51-14 transient dual interface test method (TDIM)

ORDERING INFORMATION TABLE

Device code



- 1 Vishay TMBS product
- 2 Current rating (8 = 8 A)
- Package type (N3 = DFN33A)
- Process type option (M = low I_R)
- 5 Voltage rating (10 = 100 V)
- 6 TMBS generation option (3 = Gen3)
- 7 Special option (S = special option)
- Quality grade (H = AEC-Q101 qualified, otherwise = industry grade)
- Material / environmental category (M3 = halogen-free, RoHS-compliant, and termination lead (Pb)-free)

ORDERING INFORMATION (Example)						
PREFERRED P/N	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE	BASE QUANTITY	DELIVERY MODE		
V8N3M103S-M3/I	0.031	I	6000	13" diameter plastic tape and reel		
V8N3M103SHM3/I (1)	0.031	I	6000	13" diameter plastic tape and reel		

Note

(1) AEC-Q101 qualified



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RATINGS AND CHARACTERISTICS CURVES ($T_A = 25$ °C unless otherwise noted)

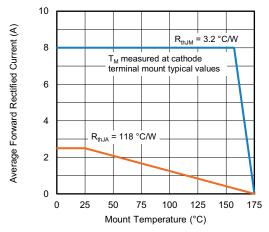


Fig. 1 - Maximum Forward Current Derating Curve

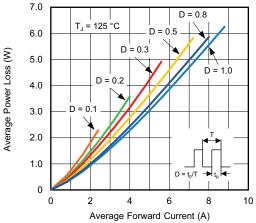


Fig. 2 - Forward Power Loss Characteristics

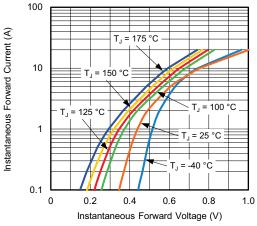


Fig. 3 - Typical Instantaneous Forward Characteristics

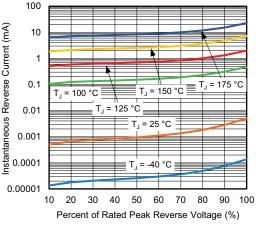


Fig. 4 - Typical Reverse Characteristics

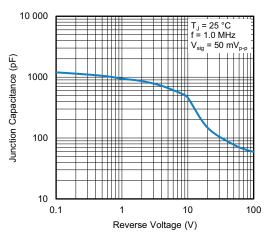


Fig. 5 - Typical Junction Capacitance

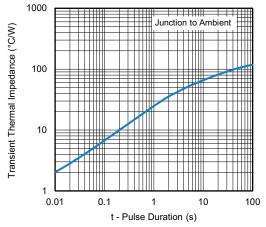


Fig. 6 - Typical Transient Thermal Impedance



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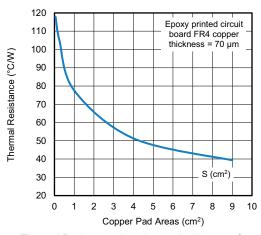
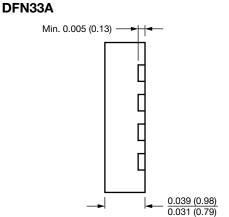
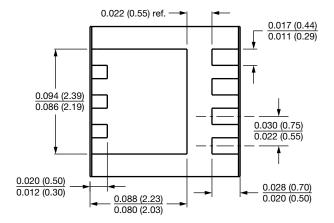


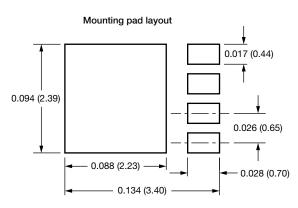
Fig. 7 - Thermal Resistance Junction-to-Ambient vs. Copper Pad Areas

PACKAGE OUTLINE DIMENSIONS in inches (millimeters)

0.134 (3.40) 0.126 (3.20) 0.134 (3.40) 0.126 (3.20)









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